



Material Content Data Sheet



Sales Product Name		IPS80R2K4P7		Issued		19. January 2018		
MA#		MA001657702						
Package		PG-TO251-3-342		Weight*		317.17 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.008	0.32	0.32	3177	3177
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		464	
	non noble metal	copper	7440-50-8	147.096	46.36	46.42	463781	464384
	non noble metal	aluminium	7429-90-5	0.148	0.05	0.05	467	467
wire	non noble metal	aluminium	7429-90-5	0.148	0.05	0.05	467	467
encapsulation	organic material	carbon black	1333-86-4	1.429	0.45		4507	
	plastics	epoxy resin	-	25.013	7.89		78865	
	inorganic material	silicondioxide	60676-86-0	116.491	36.73	45.07	367288	450660
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11792	11792
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4479	4490
solder	non noble metal	tin	7440-31-5	0.028	0.01		90	
	noble metal	silver	7440-22-4	0.036	0.01		112	
	non noble metal	lead	7439-92-1	1.359	0.43	0.45	4284	4486
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60465	60544
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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